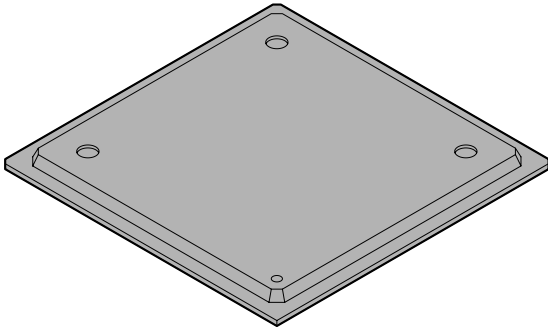
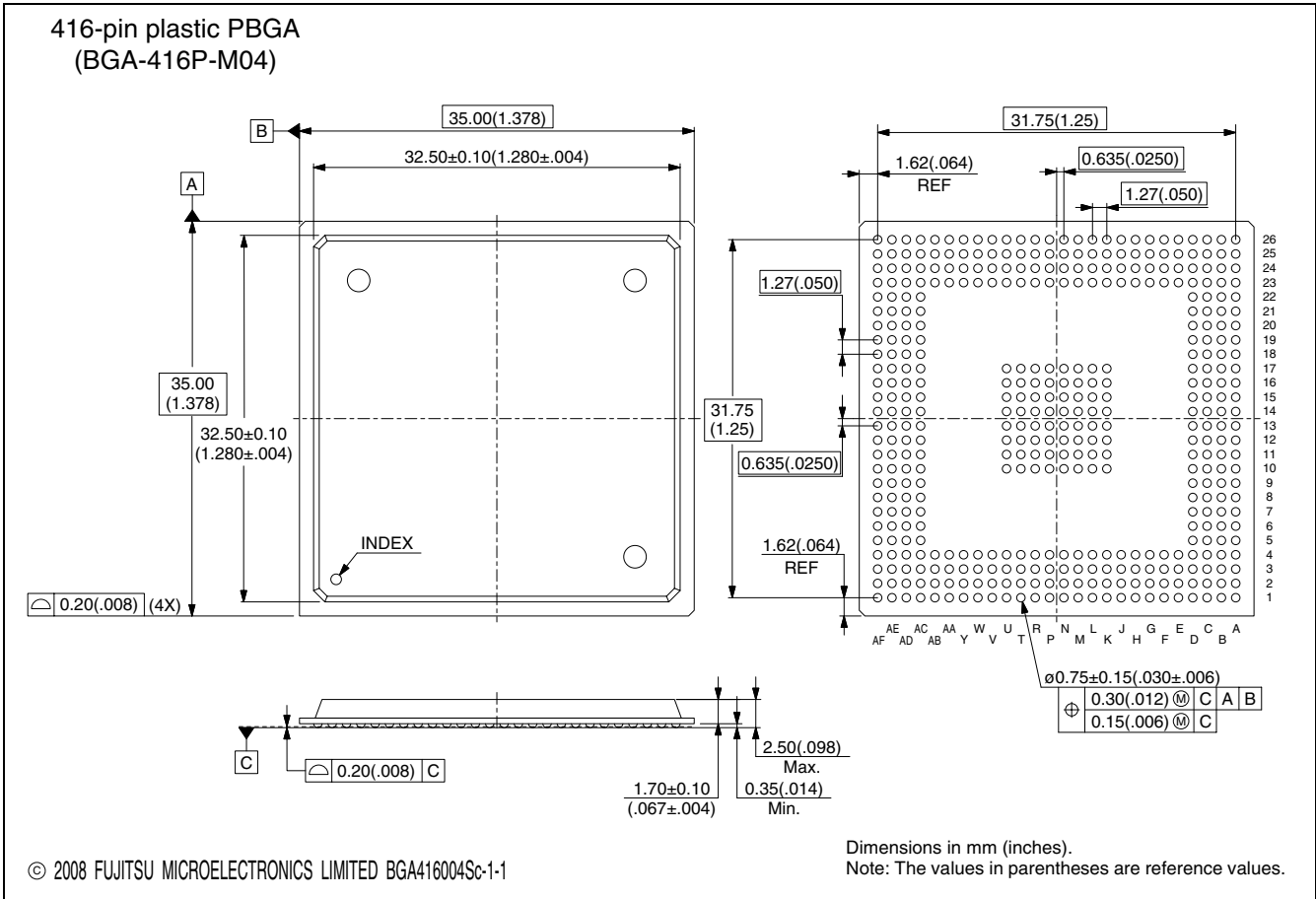


**BGA-416P-M04**

<p>416-pin plastic PBGA</p>  <p>(BGA-416P-M04)</p>	Lead pitch	1.27 mm
	Package width × package length	35.00 mm × 35.00 mm
	Lead shape	Ball
	Sealing method	Plastic mold
	Mounting height	2.50 mm MAX
	Weight	4.40 g



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Customers are advised to consult with FUJITSU MICROELECTRONICS sales representatives before ordering.  
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